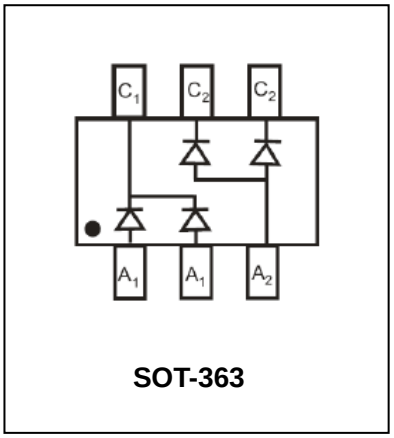
Surface Mount Fast Switching Diodes BAW567DW

FEATURES

- Fast switching speed.
- For general purpose switching application.
- Ultra-small surface mount package.
- High conductance.

Lead-free



SOT-363

APPLICATIONS

- For general purpose switching application.

ORDERING INFORMATION

Type No.	Marking	Package Code
BAW567DW	KAC	SOT-363

MAXIMUM RATING @ Ta=25℃ unless otherwise specified

Symbol	**Characteristic**	**Value**	**Unit**
V_R	DC reverse voltage	75	V
I_F	Forward continuous current	150	mA
P_D	Power Dissipation	200	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	625	℃/W
T_j, T_{stg}	Junction and Storage Temperature	-55 to+150	℃

ELECTRICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

Surface Mount Fast Switching Diodes BAW567DW

Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Reverse breakdown voltage	$V_{(BR)R}$	I_R=2.5μA	75	-	V
Forward voltage	V_F	I_F=1.0mA I_F=10mA I_F=50mA I_F=150mA	-	0.715 0.855 1.0 1.25	V
Reverse voltage leakage current	I_R	V_R=75V V_R=20V		2.5 0.025	μA
Junction Capacitance	C_J	V_R=0V,f=1.0MHz	-	2.0	pF
Reverse Recovery time	t_{rr}	I_F=I_R=10mA,I_{rr}=0.1*I_R, R_L=100Ω	-	4.0	ns

TYPICAL CHARACTERISTICS @ Ta=25℃ unless otherwise specified

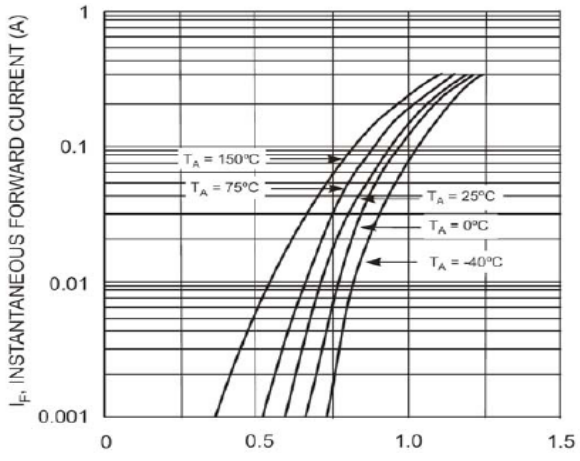


Fig. 1 Forward Characteristics

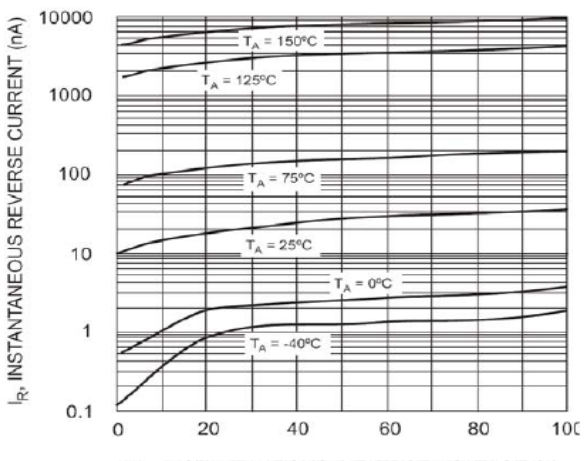


Fig. 2 Typical Reverse Characteristics

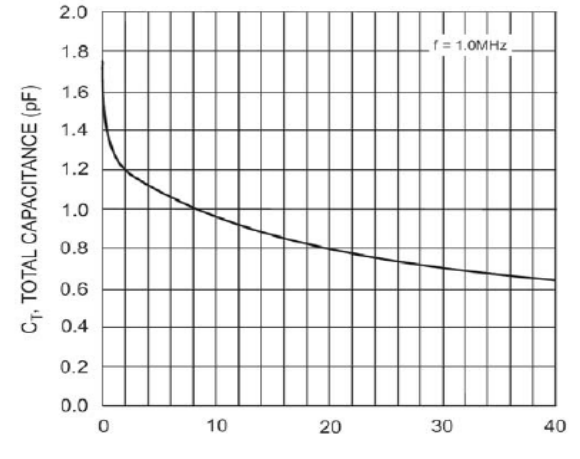


Fig. 3 Typical Capacitance vs. Reverse Voltage

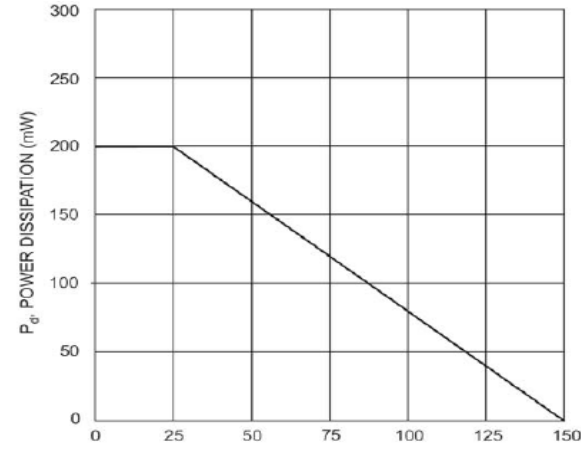
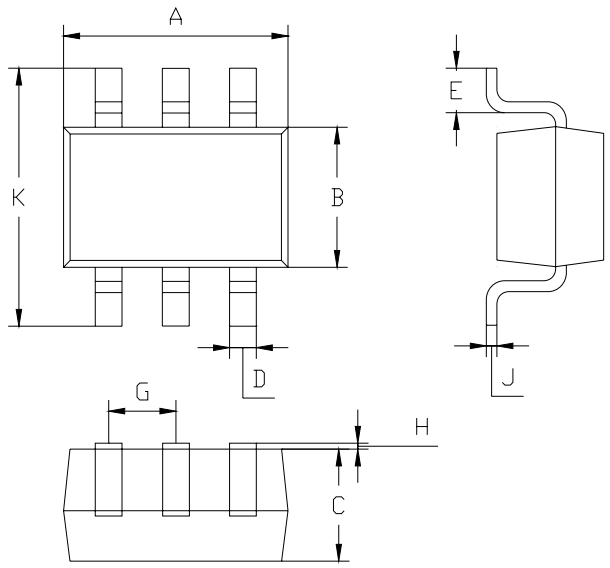


Fig. 4 Power Derating Curve

Surface Mount Fast Switching Diodes BAW567DW

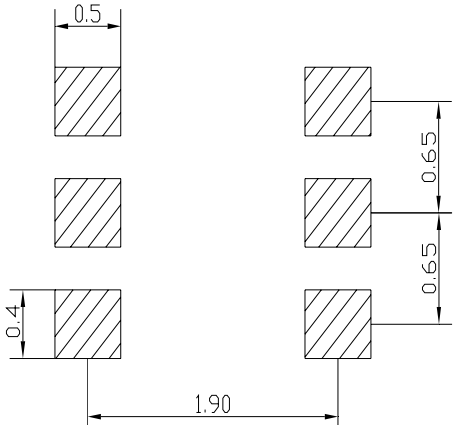
PACKAGE OUTLINE

Plastic surface mounted package SOT-363



SOT-363		
Dim	Min	Max
A	1.8	2.2
B	1.15	1.35
C	1.0Typical	
D	0.10	0.30
E	0.25	0.40
G	0.65Typical	
H	0.02	0.10
J	0.1Typical	
K	2.1	2.3
All Dimensions in mm		

SOLDERING FOOTPRINT



Unit : mm

PACKAGE INFORMATION

Device	Package	Shipping
BAW567DW	SOT-363	3000/Tape&Reel